





Machine performance	Specifications
Alignment	@ ±12.5 μm*
Machine accuracy	> 2,0 C _{mk} @ ±25 μm, (6 sigma)**
Shortest core cycle time (CCT)	11 seconds (8 seconds with option)
Operating system	Windows 7 Standard embedded
Squeegee pressure	Software-controlled, motorized with ±1 kg closed-loop feedback
Stencil positioning	Depth stop or semi-automatic stencil loading (optional)
Stencil mount	736 mm x 736 mm (29" x 29") or flexible stencil width adjustment for sizes ranging from 381 mm to 736 mm with frame thickness ranging from 25 mm to 38 mm (optional)
Understencil cleaning	300/400/520 mm DEK Interchangeable Under Stencil Cleaner (DEK IUSC), programmable for wet, dry and vacuum cleaning
Substrate sizes	50 mm (X) x 40.5 mm (Y) to 510 mm (X) x 508.5 mm (Y)
Substrate thicknesses	0.2 mm to 6 mm
Product changeover	< 2 min***
Program creation	< 10 minutes***
Substrate clamping	Over-the-top clamping (OTT) Lateral clamping (optional) Substrate vacuum (optional)
Temperature and humidity sensors	Statistical recording of temperature and humidity readings
Paste verification	Hawkeye 750 (optional)

^{*} Alignment accuracy is calculated with third-party QC-Calc software and comprises substrate loading/unloading, clamping, and the movement of camera systems and tables.



The **NEW** member of the E Solutions: E by DEK

The total package makes the difference!
E by DEK – as individual as your requirements

^{**} Machine capability is calculated with third-party QC-Calc software and comprises substrate loading/unloading, clamping, and the movement of camera systems and tables.

^{***} Under optimal conditions





The E-Solutions line from ASM is now complete!

Maximum Transparency

with ASM E-Line Monitor

The E by SIPLACE has already set new standards in quality, performance and ease of use in the mid-speed placement segment. Now it is being joined by the ideal printer solution: E by DEK.

The result: E-Solutions, the all-round line solution for the mid-speed segment with integrated software solutions, line monitoring, traceability and fast, trouble-free setup processes for high-mix contract manufacturers and the production of small batches and prototypes.

E-quality

· Modular design

· Core cycle times of as little

· Top ratings in speed, quality,

changeover efficiency and

· Application Packs available

as 8 seconds

repeat accuracy

for any requirement

- · High-quality components ensure stable and reliable printing processes even for today's fine-pitch applications
- · Maximum transparency with the ASM E-Line Monitor





E by DEK – as flexible as your applications

Is your production changing? Instead of having to invest in new printer models, the E by DEK always has the right answer thanks to a wide range of options. They make the E by DEK exceptionally flexible and protect your investment.

Always the right option for your applications:

Throughput

Turn your E by DEK into a high-speed solution

- · Core cycle time as short as 8 seconds
- · Dual-speed conveyor motor for soft stops
- State-of-the-art clamping and loading systems

Quality

Optimize your paste application process:

- Paste inspection system
- State-of-the-art process control software
- · DEK Paste Roll Height Monitor

Flexibility

Unique in its class. E by DEK - as flexible as your applications

- Lateral clamping
- · Dual-speed conveyor motor for soft stops
- · Variable stencil loading
- Fast semi-automatic stencil loading

E-flexibility

- · Easy operation with intuitive user interface
- · Broad selection of accessories ranging from software options to automatic stencil width adjustment
- · Everything under control: Keep an eye on the whole line with the E-Line Monitor
- Patented clamping system
- · Modular construction for maximum flexibility



Long and heavy boards

In the mid-speed segment, only the E by DEK can print long and heavy boards:

- Boards with lengths of up to 620 mm
- DEK conveyor for heavy substrates (Heavy Board Rails)
- Camera-independent substrate stop (DEK Remote Board Stop)
- Long-board understencil cleaning (600 mm)